

# Advance Technical Information

# **Linear Power MOSFET** With Extended FBSOA

# **IXTN8N150L**

N-Channel Enhancement Mode Avalanche Rated



#### $\mathbf{V}_{\text{dss}}$ = 1500V= 8A D25 = 5.0Ω R<sub>DS(on)</sub>

miniBLOC, SOT-227 B (IXTN) **E153432** 



G = Gate D = Drain S = Source

# S = Source

### **Features**

- Designed for linear operations
- International standard package
- Unclamped Inductive switching (UIS) rated
- Molding epoxies meet UL94 V-0 flammability classification
- miniBLOC with Aluminum nitride isolation
- Low R<sub>DS(on)</sub> HDMOS<sup>™</sup> process
   Rugged polysilicon gate cell structure
- Low package inductance

### Applications

- Programmable loads
- Current regulators
- DC-DC convertors
- Battery chargers
- DC choppers
- Temperature and lighting controls

### Advantages

- · Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Maximum Ratings				
V <sub>DSS</sub>	$T_{J} = 25^{\circ}C$ to $150^{\circ}C$	1500	V			
V <sub>dgr</sub>	$T_{J} = 25^{\circ}C$ to 150°C, $R_{GS} = 1M\Omega$	1500	V			
V <sub>gss</sub>	Continuous	±30	V			
V <sub>GSM</sub>	Transient	±40	V			
D25	$T_c = 25^{\circ}C$	8	A			
AR	$T_c = 25^{\circ}C$	22	A			
ом	$T_{_{ m C}}$ = 25°C, pulse width limited by $T_{_{ m JM}}$	15	A			
<b>E</b> <sub>AR</sub>	$T_c = 25^{\circ}C$	60	mJ			
E <sub>AS</sub>	$T_c = 25^{\circ}C$	1.5	J			
<b>P</b> <sub>D</sub>	$T_c = 25^{\circ}C$	700	W			
T_		-55 to +150	°C			
T <sub>JM</sub>		150	°C			
T <sub>stg</sub>		-55 to +150	°C			
V	50/60 Hz, RMS, t = 1minute	2500	٧~			
ISOL	$I_{ISOL} \le 1 m A, \qquad t = 1 s$	3000	V~			
M <sub>d</sub>	Mounting torque for Base Plate Terminal connection torque	1.5/13 1.3/11.5	Nm/lb.in. Nm/lb.in.			
Weight		30	g			

<b>Symbol</b> (T <sub>J</sub> = 25°C, 1	′acteristic Values │Typ. │ Max.				
BV <sub>DSS</sub>	$V_{gs} = 0V, I_{D} = 1mA$	1500			V
V <sub>GS(th)</sub>	$V_{_{DS}} = V_{_{GS}}, I_{_{D}} = 250 \mu A$	3.0		5.0	V
I <sub>gss</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$			±200	nA
I <sub>DSS</sub>	V <sub>DS</sub> = V <sub>DSS</sub>			50	μA
	$V_{gs} = 0V$ $T_{J} = 125^{\circ}C$			5	mA
R <sub>DS(on)</sub>	$V_{_{\rm GS}}$ = 20V, $I_{_{\rm D}}$ = 0.5 • $I_{_{\rm D25}}$ , Note 1			5.0	Ω

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# IXTN8N150L

Symbol	aracteristic Values				
(T <sub>J</sub> = 25	ö°C, ι	inless otherwise specified)	Min.	Тур.	Max.
<b>g</b> <sub>fs</sub>		$V_{_{DS}}$ = 50V, $I_{_{D}}$ = 0.5 • $I_{_{D25}}$ , Note 1	2.0	3.5	6.0 S
C <sub>iss</sub>	)			7900	pF
C <sub>oss</sub>	}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		420	pF
$\mathbf{C}_{rss}$	J			72	pF
t <sub>d(on)</sub>	١	Peolotive Switching Times		46	ns
t,				55	ns
t <sub>d(off)</sub>	1	$V_{gs} = 15V, V_{Ds} = 0.5 \bullet V_{Dss}, I_{D} = 0.5 \bullet I_{D25}$		73	ns
$t_f$	J	$R_{g} = 2\Omega (External)$		75	ns
Q <sub>g(on)</sub>	)			250	nC
Q <sub>gs</sub>	}	$V_{gs} = 15V, V_{Ds} = 0.5 \bullet V_{Dss}, I_{D} = 0.5 \bullet I_{D25}$		60	nC
$\mathbf{Q}_{gd}$	J			80	nC
R <sub>thJC</sub>					0.18 °C/W
$\mathbf{R}_{_{\mathrm{thCS}}}$				0.05	°C/W



(M4 screws (4x) supplied)

CVM	INCH	IES	MILLIMETERS			
SIM	MIN	MAX	MIN	MAX		
A	1.240	1.255	31.50	31.88		
В	.307	.323	7.80	8.20		
С	.161	.169	4.09	4.29		
D	.161	.169	4.09	4.29		
E	.161	.169	4.09	4.29		
F	.587	.595	14.91	15.11		
G	1.186	1.193	30.12	30.30		
Н	1.496	1.505	38.00	38.23		
J	.460	.481	11.68	12.22		
K	.351	.378	8.92	9.60		
L	.030	.033	0.76	0.84		
М	.496	.506	12.60	12.85		
Ν	.990	1.001	25.15	25.42		
0	.078	.084	1.98	2.13		
Р	.195	.235	4.95	5.97		
Q	1.045	1.059	26.54	26.90		
R	.155	.174	3.94	4.42		
S	.186	.191	4.72	4.85		
Т	.968	.987	24.59	25.07		
U	002	.004	-0.05	0.1		

#### Safe Operating Area Specification

Symbol	Test Conditions	Cł	Characteristic Values			
		Min.	Тур.	Max.		
SOA	$V_{_{DS}} = 800V, I_{_{D}} = 0.3A, T_{_{C}} = 90^{\circ}C$	240		W		

### Source-Drain Diode

Symbol	Test Conditions	Characteris					
$(T_{J} = 25^{\circ}C)$	unless otherwise specified)	Min.	Тур.	Max.			
I <sub>s</sub>	$V_{GS} = 0V$			8	A		
I <sub>SM</sub>	Repetitive, pulse width limited by $T_{_{JM}}$			15	A		
V <sub>SD</sub>	$I_{_{\rm F}}$ = 4A, $V_{_{ m GS}}$ = 0V, Note 1			5.5	V		
t <sub>rr</sub>	$I_{_{\rm F}} = I_{_{\rm S}}$ , -di/dt = 500A/µs $V_{_{\rm R}} = 200V$		790		ns		

Notes: 1. Pulse test, t  $\leq$  300 $\mu$ s; duty cycle, d  $\leq$  2%.

### **ADVANCE TECHNICAL INFORMATION**

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
by one or moreof the following U.S. patents:	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	